

# PM002N100DM

100V 120A 2.6mΩ Single N channel Trench MOSFET with Normal Diode

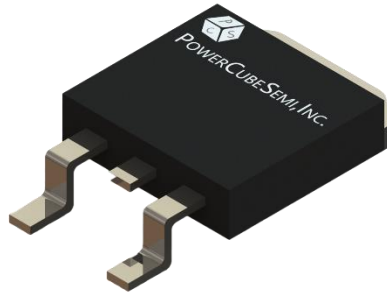
## Features

### Si Single N channel Trench MOSFET

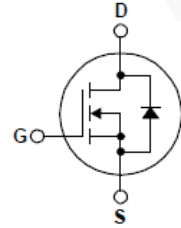
- Rated to 100V at 120Amps @ $T_j = 25^\circ\text{C}$
- Max  $R_{DS(on)} = 2.6\text{ m}\Omega$
- Typ  $R_{DS(on)} = 2.3\text{ m}\Omega$
- Gate Charge(Typ.  $Q_g=147\text{ nC}$ )
- 100% UIL Tested
- 100% Rg Tested

## Application

- Industrial Application
- Electric Bike
- DC/DC Converter
- General purpose Application



PKG type : TO-263(D2PAK)



## Description

PM002N100DM uses advanced PowerCubeSemi's MOSFET technology, which provides high performance in on-state resistance, fast switching performance, and excellent quality. These devices can also be utilized in industrial applications such as Low power drives of E-bike (E-Vehicles), DC/DC converter, and general purpose applications.

## Absolute Maximum Ratings

Symbol	Parameter	Test Condition	Value	Unit
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS}=0V, I_D=250\mu A$	100	V
$I_D$	Drain Current	$T_c=25^\circ\text{C}$	120	A
$I_{DM}$	Pulsed Drain Current	Pulse width limited by junction temperature	480	A
$V_{GS}$	Gate-Source Voltage		$\pm 20$	V
$E_{AS}$	Single Pulsed Avalanche Energy	$I_{AS}=32A, V_{GS}=10V, L=1.0mH$	512	mJ
$P_d$	Power Dissipation	$T_c=25^\circ\text{C}$	416	W
$T_j$	Operating Junction Temperature		175	$^\circ\text{C}$
$T_{stg}$	Storage Temperature		-55 to 175	$^\circ\text{C}$



## Package Marking and Ordering Information

Device Marking	Device	Package	Packing Method	Tape width	Quantity
PM002N100DM	PM002N100	TO-263	Tube & Reel	-	

## Electrical Characteristics of Si MOSFET

Symbol	Parameter	Test Condition	Numerical			Unit
			Min	Typ.	Max.	
$BV_{DSS}$	Drain-Source Breakdown Voltage	$V_{GS} = 0V, I_D = 250\mu A, T_J = 25^\circ C$	100	-	-	V
$I_{DSS}$	Zero Gate Voltage Drain Current	$V_{DS} = 100V, V_{GS} = 0V$	-	-	1	$\mu A$
$I_{GSS}$	Gate-Source Leakage Current	$V_{GS} = \pm 20V, V_{DS} = 0V$	-	-	$\pm 100$	nA
$V_{GS(th)}$	Gate Threshold Voltage	$V_{DS} = V_{GS}, I_D = 250\mu A$	2	-	4	V
$R_{DS(ON)}$	Static Drain-Source on state Resistance	$V_{GS} = 10V, I_D = 50A$	-	2.3	2.6	m $\Omega$
$g_{FS}$	Forward Transconductance	$V_{DS} = 10V, I_D = 50A$	-	110	-	S
$t_{d(on)}$	Turn-on Delay time	$V_{DS} = 50V, I_D = 50A, V_{GS} = 10V, R_G = 3\Omega$	-	33	-	ns
$T_r$	Turn-on Rise time		-	20	-	
$t_{d(off)}$	Turn-off Delay time		-	123	-	
$T_f$	Turn-off Fall time		-	45	-	



## Electrical Characteristics of Si MOSFET

Symbol	Parameter	Test Condition	Numerical		Unit
			Typ.	Max.	
$R_{\theta JC}$	Thermal Resistance, Junction to Case		0.36	-	$^{\circ}\text{C}/\text{W}$
$R_g$	Gate Resistance	$V_{GS} = 0\text{V}, f = 1.0\text{MHz}$	3	-	$\Omega$
$C_{iss}$	Input Capacitance	$V_{DS} = 40\text{V}, V_{GS} = 0\text{V}, f = 1.0\text{MHz}$	10420	-	pF
$C_{oss}$	Output Capacitance		2050	-	
$C_{rss}$	Reverse Transfer Capacitance		36	-	
$Q_{g(\text{tot})}$	Total Gate Charge at 10V	$V_{DS} = 50\text{V}, I_D = 50\text{A}$ $V_{GS(\text{on})} = 10\text{V}$	147	-	nC
$Q_{gs}$	Gate to Source Gate Charge		42	-	
$Q_{gd}$	Gate to Drain "Miller" Charge		28	-	

## Electrical Characteristics of Si Diode

Symbol	Parameter	Test Condition	Numerical		Unit
			Typ.	Max.	
$I_S$	Maximum Continuous Drain to Source Diode Forward Current		-	120	A
$I_{SM}$	Maximum Pulsed Drain to Source Diode Forward Current		-	480	A
$V_{SD}$	Drain to Source Diode Forward Voltage	$I_S = 50\text{A}, V_{GS} = 0\text{V}$	0.9	1.2	V
$T_{rr}$	Reverse Recovery Time	$I_S = 50\text{A}, dI/dt = 100\text{A}/\mu\text{s}$	98	-	ns
$Q_{rr}$	Reverse Recovery Charge		275	-	nC

# Typical Characteristics

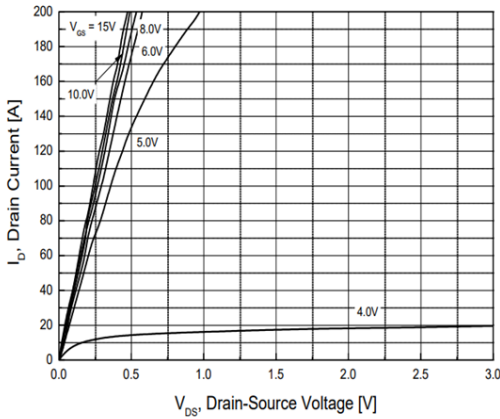


Figure 1. On-Region Characteristics

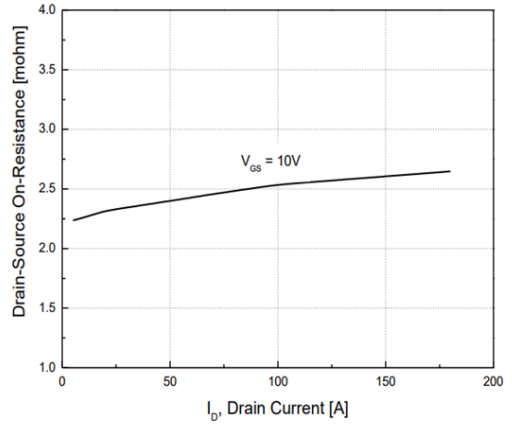


Figure 2. On-Resistance Variation with Drain Current and Gate Voltage

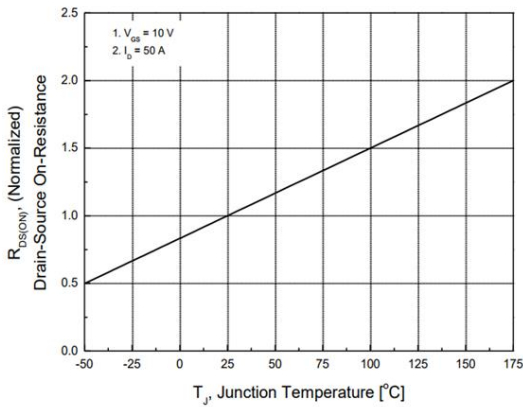


Figure 3. On Resistance Variation with Temperature

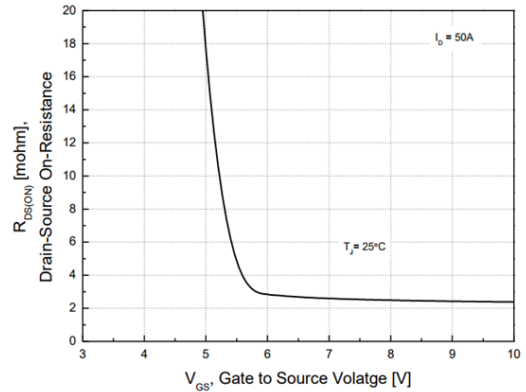


Figure 4. On-Resistance Variation with Gate to Source Voltage

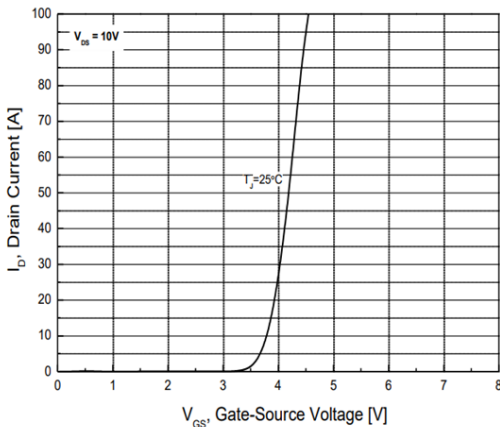


Figure 5. Transfer Characteristics

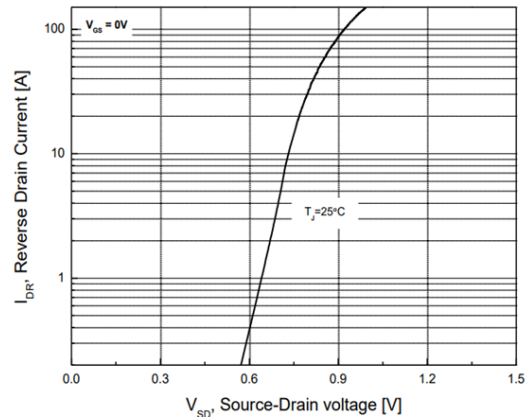


Figure 6. Body Diode Forward Voltage Variation with Source Current and Temperature

# Typical Characteristics

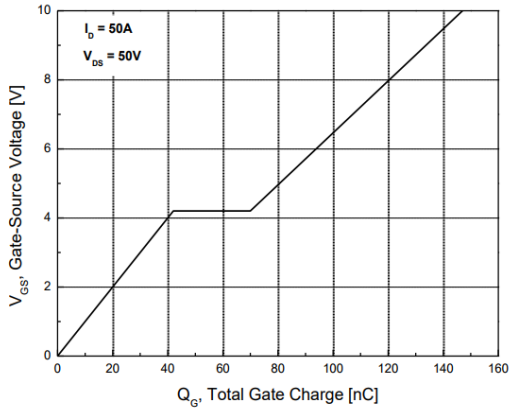


Figure 7. Gate Charge Characteristics

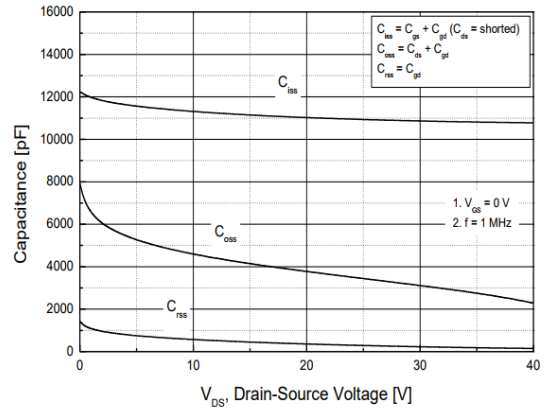


Figure 8. Capacitance Characteristics

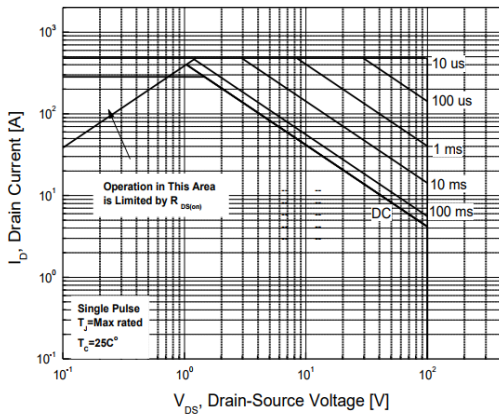


Figure 9. Maximum Safe Operating Area

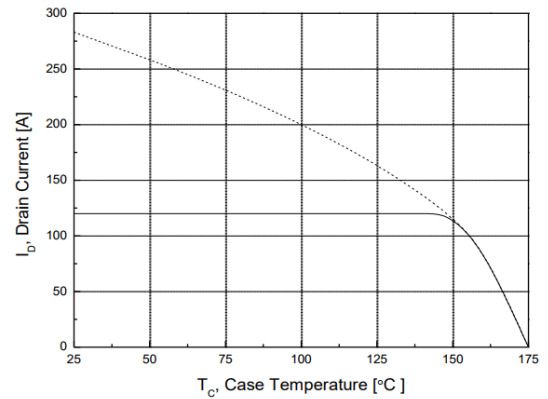


Figure 10. Maximum Drain Current vs. Case Temperature

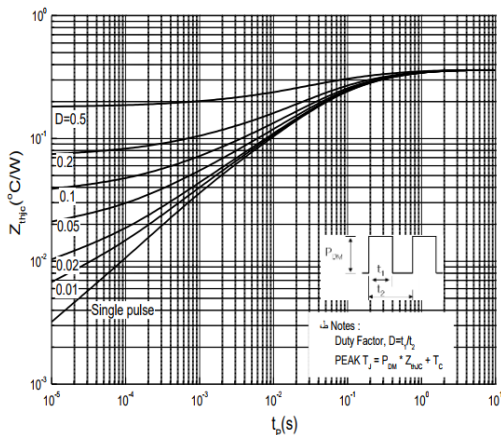
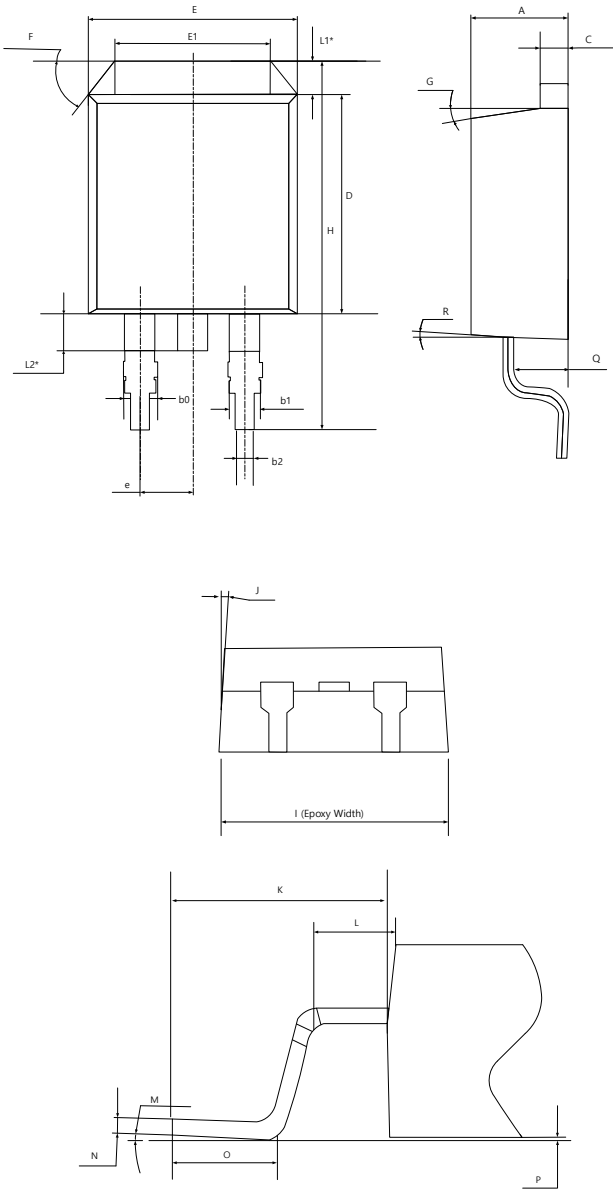


Figure 11. Transient Thermal Response Curve

**Package Outline**

Unit : mm



SYMBOL	DIMENSIONS			NOTES
	MIN	NOM	MAX	
<b>A</b>	4.40	4.60	4.80	
<b>b0</b>	1.17	1.37	1.57	
<b>b1</b>	1.17	1.27	1.37	
<b>b2</b>	0.70	0.80	0.90	
<b>C</b>	1.17	1.27	1.37	
<b>D</b>	8.50	8.70	8.90	
<b>E</b>	9.80	10.00	10.20	
<b>E1</b>	6.50	-	-	
<b>e</b>	2.44	2.54	2.64	
<b>F</b>	-	30° (Ref)	-	
<b>G</b>	-	7.0°	-	
<b>H</b>	15.00	15.30	15.60	
<b>I</b>	9.80	10.00	10.20	
<b>J</b>	-	3.0°	-	
<b>K</b>	5.00	5.30	5.60	
<b>L</b>	1.80	2.00	2.20	
<b>L1</b>	1.07	1.27	1.47	
<b>L2</b>	1.20	1.50	1.80	
<b>M</b>	0.0°	-	8.0°	
<b>N</b>	0.30	0.45	0.60	
<b>O</b>	2.34	2.54	2.74	
<b>P</b>	0	-	0.25	
<b>Q</b>	2.37	2.67	2.97	
<b>R</b>	-	7.0°	-	